FLIP CHIP BONDER-A110

High Productivity
- 15,000 UPH (Based on Dry Run)

Mass Defect Protection Capability
- Flux, Die Tilt, Ejector Pin Missing, Contamination

Precision Bonding Capability
- ± 6μm @ 3σ

Thin Die / Small Die Capability
- Min. 40μm Thickness / Min. 0.4mm x 0.4mm

HANMI Semiconductor
FLIP CHIP BONDER
A110

Enhanced Machine Features

- High Productivity
  - 15,000 UPH (Based on Dry Run)
  - Dual Bonding Head
  - Hanmi Special Sequence Profile
  - Enhanced Temperature Control System

- Precision Bonding Capability
  - ± 6µm @ 3σ
  - Supreme Vision Inspection System
  - High Accurate Gantry Structure
  - Lower Vibration Control System
  - One Casting Body Structure

- Mass Defect Protection Capability
  - Hanmi Special Flux Vision Inspection System
  - Auto Flatness Check System
  - Wafer Map Shift Prevent Function
  - Foreign Material Detect Inspection System
  - Ejector Pin Missing Inspection System
  - Chip Out Detect Inspection System
  - Multi Reject Mark Reading Capability

- User Friendly & Easy Operation
  - Windows Based HMI Screen
  - Easy & Quick Conversion
  - Easy Maintenance

“New Technology”
Flux Vision Inspection

Non-wet Free!

Eject Cup F/M

Die Chipout Inspection
Eject Cup F/M
Water Ejector Pin Maker Inspection

Components and Substrates

<table>
<thead>
<tr>
<th>Component</th>
<th>Specification</th>
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</thead>
<tbody>
<tr>
<td>Water</td>
<td>Die Size: 0.4mm x 0.4mm</td>
</tr>
<tr>
<td></td>
<td>Die Thickness: 0.04mm – 0.0mm</td>
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<tr>
<td></td>
<td>Wafer Size: Up to 12”</td>
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<tr>
<td>Substrate</td>
<td>Width: 218mm – 200mm</td>
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<tr>
<td></td>
<td>Length: 50mm – 300mm</td>
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</tbody>
</table>

Performance

<table>
<thead>
<tr>
<th>Feature</th>
<th>Specification</th>
<th>MTBF</th>
<th>MTTR</th>
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<tbody>
<tr>
<td>Productivity</td>
<td>15,000 (Based on Dry Run)</td>
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<tr>
<td>Accuracy</td>
<td>± 6µm @ 3σ</td>
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<tr>
<td>Bonding Head</td>
<td>± 0.1 @ 3σ</td>
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<tr>
<td>Bonding Force</td>
<td>1N – 2N (Programmable from 1N)</td>
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<tr>
<td>Footprint</td>
<td>1,600mm x 1,200mm x 1,500mm</td>
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<td></td>
<td>2700 kg</td>
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